

To: Technology Center 2800  
Facsimile Number: ~~792-972-9886~~

NOV 11 2005

Total Pages Sent 13

From: Charles A. Brill  
Texas Instruments Incorporated  
Facsimile: 972-917-4418  
Phone: 972-917-4379

571-273-8306

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

## CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by  
facsimile to the U.S. Patent and Trademark Office on the date  
shown below:

  
Charles A. Brill

November 11, 2005  
Date

## FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (11 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT (2 Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL BRIEF (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> PETITION
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S):	
Mezenner	
RECEIPT DATE & SERIAL NO.:	
Application No.: 10/749,277	
Filing Date: 31 December 2003	
TITLE OF INVENTION:	
VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
TI FILE NO.:	DEPOSIT ACCT. NO.:
TI-33824	20-0668
FAXED: 11/11/2005	
DUE: 9/12/2005	
ATTY/SECY: CAB:ss	

RECEIVED  
OPIE/IAP

NOV 15 2005

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75265